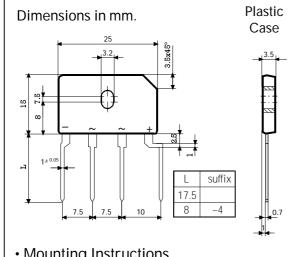
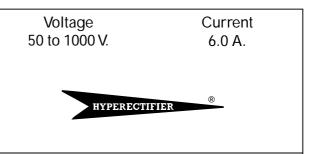




6 Amp. Glass Passivated Bridge Rectifier



- Mounting Instructions
- High temperature soldering guaranteed: 260 °C 10 sc.
- Recommended mounting torque: 8 Kg.cm.



- · Glass Passivated Junction Chips.
- UL recognized under component index file number E130180.
- · Lead and polarity identifications.
- · Case: Molded Plastic.
- Ideal for printed circuit board (P.C.B.).
- · High surge current capability.
- The plastic material carries U/L recognition 94 V-O.

Maximum Ratings, according to IEC publication No. 134

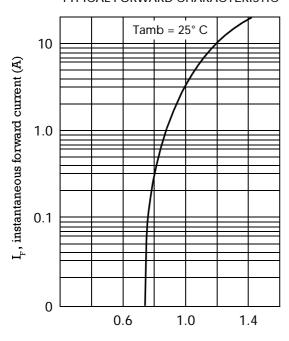
		FBI6A 1M1	FBI6B 1M1	FBI6D 1M1	FBI6G 1M1	FBI6J 1M1	FBI6K 1M1	FBI6M 1M1
VRRM	Peak recurrent reverse voltage (V)	50	100	200	400	600	800	1000
V _{RMS}	Maximum RMS voltage (V)	35	70	140	280	420	560	700
I _{F(AV)}	Max. Average forward current with heatsink without heatsink	6.0 A at 100 °C 3.0 A at 40 °C						
I _{FSM}	10 ms. peak forward surge current (Jedec Method)	170 A						
I ² t	Current squared time (rating for fusing) (1ms. <t<10ms. tc="25°C)</td"><td colspan="6">140 A² sec</td></t<10ms.>	140 A ² sec						
VDIS	Dielectric strength (terminals to case, AC 1 min.)	2000 V						
T_{j}	Operating temperature range	− 55 to + 150 °C						
T_{stg}	Storage temperature range	− 55 to +150 °C						

Electrical Characteristics at Tamb = 25°C

V _F	Max. forward voltage drop per diode at $I_F = 3.0 \text{ A}$	1.05 V
I _R	Max. instantaneous reverse current at V _{RRM}	5μΑ
	MAXIMUM THERMAL RESISTANCE	
R _{th (j-c)}	Junction-Case. With Heatsink.	2.2 °C/W
$R_{th\ (j-a)}$	Junction-Ambient. Without Heatsink.	22 °C/W

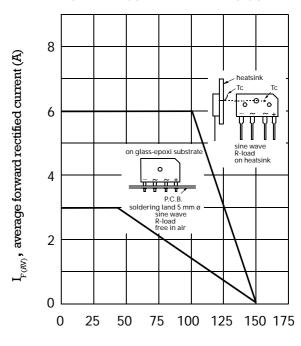


TYPICAL FORWARD CHARACTERISTIC



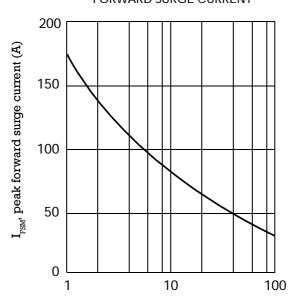
 $V_{_{\rm F}}$, instantaneous forward voltage (V)

FORWARD CURRENT DERATING CURVE



Tamb, ambient temperature (°C)

MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



Number of cycles at 50 Hz.